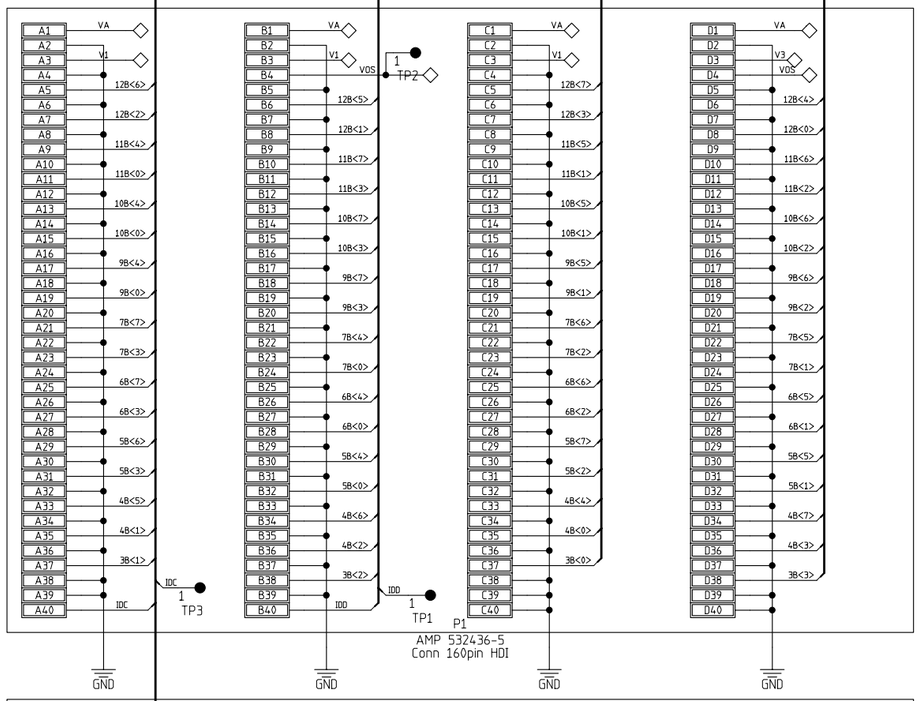
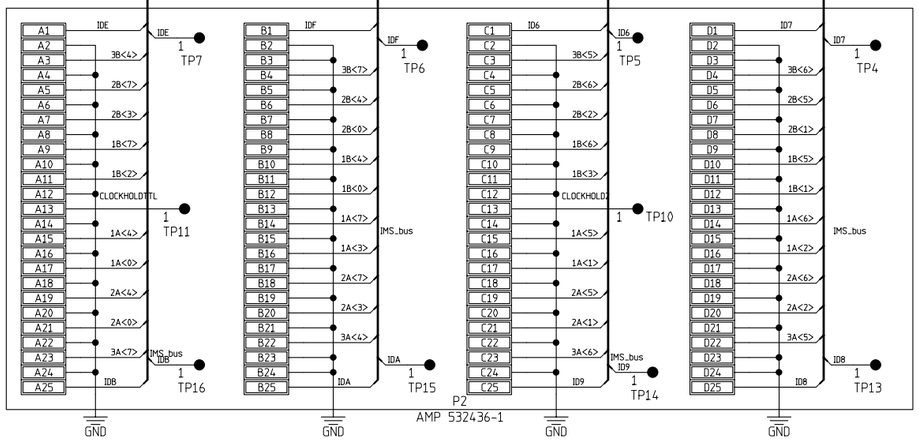
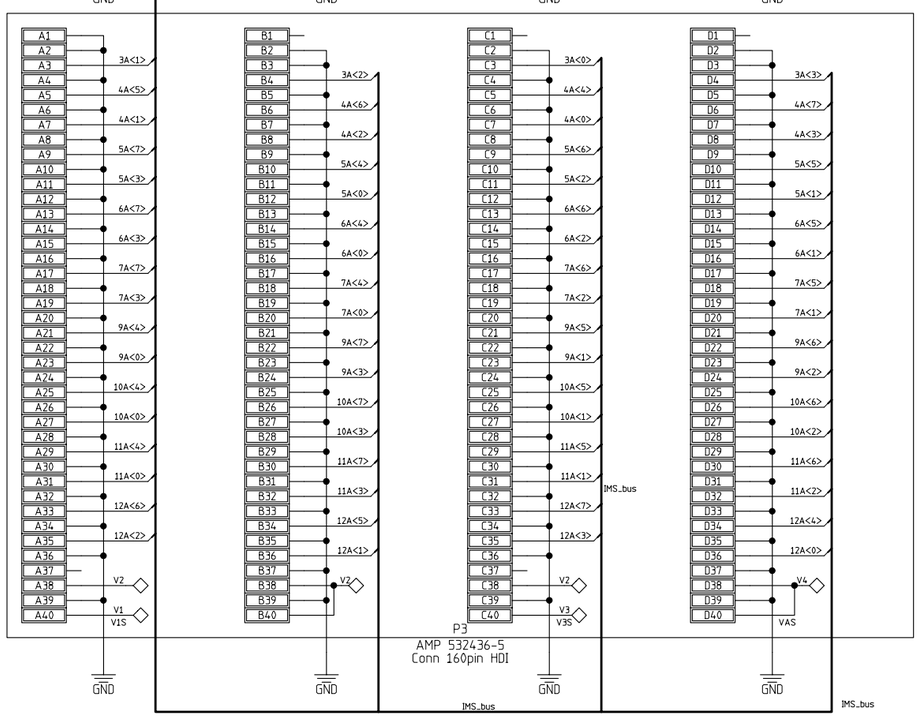
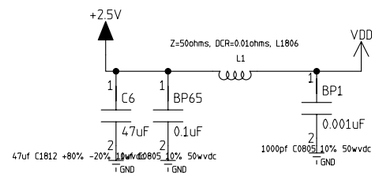
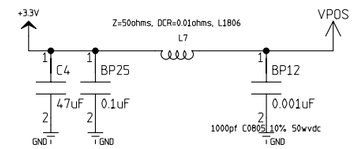
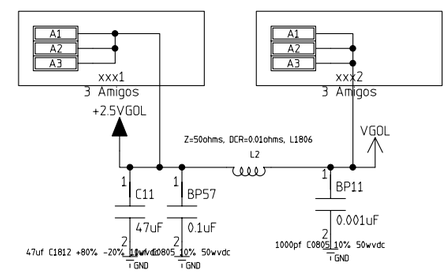


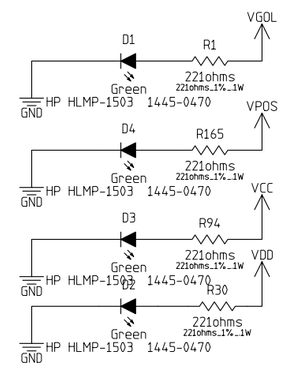


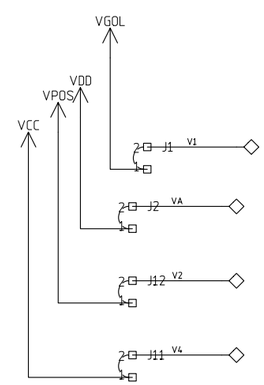




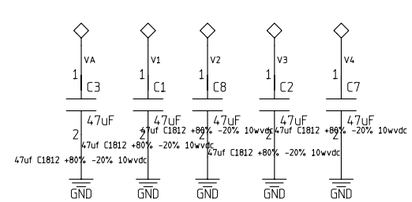


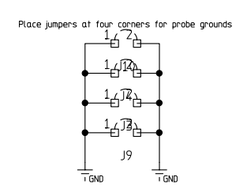






1) The ground planes for the GOL and the TLK and GLINK chips must be separated
2) The power for the GOL and VCEL must be separate
3) clock lines from IMS are terminated to ground with 50 ohms.
4) the IMS will supply 40Mhz and 80Mhz on separate pins.
5) the VCEL will be placed on the bottom of PCB as close as possible to the GOL output.
6) The GOL laser transmition line is 25ohms
7) all other GOL lines are 50 ohms
8) all outputs to IMS need a series terminator
10) The RF fan out MC100EP111FA must be routed carefully. The output resisters must be placed close to the MC100EP111FA.





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Fermi National Accelerator Laboratory
United States Department of Energy

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